-	5719	((pressure$4 near6 (test$4 detect$4 inspect$4 measur$4 sens$4 gauge indicat$4 estimat$4evaluat$4 calculate$4determin$4 identif$4 transducer cell monitor$4 comput44).clm.) and (gas fluid liquid steam air water).clm.) and heat$4.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:08
-	244	(((pressure$4 near6 (test$4 detect$4 inspect$4 measur$4 sens$4 gauge indicat$4 estimat$4evaluat$4 calculate$4determin$4 identif$4 transducer cell monitor$4 comput44).clm.) and (gas fluid liquid steam air water).clm.) and heat$4.clm.) and substrate.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:08
-	88	(pressure$4 near6 (test$4 detect$4 inspect$4 measur$4 sens$4 gauge indicat$4 estimat$4evaluat$4 calculate$4determin$4 identif$4 transducer cell monitor$4 comput44).clm.) and (gas fluid liquid steam air water) and heat$5 near3 (membrane deformable elastic$4 resilien$5 diaphragm).clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:11
-	14	((pressure$4 near6 (test$4 detect$4 inspect$4 measur$4 sens$4 gauge indicat$4 estimat$4evaluat$4 calculate$4determin$4 identif$4 transducer cell monitor$4 comput44).clm.) and (gas fluid liquid steam air water) and heat$5 near3 (membrane deformable elastic$4 resilien$5 diaphragm).clm.) and substrate.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:11
-	2	("5511428").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	2647	"5" and stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	0	(("5511428").PN.) and stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	186187	(thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:37
-	92332	((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)) and (gap groove dip recess$4 space opening hole crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:29
-	68	(((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)) and (gap groove dip recess$4 space opening hole crack)) and (wafer$4 layer$4 substrate$4 disk$4 film$4) same stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:30
-	7769	(thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:29
-	2750814	"8" and (gap groove dip recess$4 space opening hole crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:30

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-	3643	((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (gap groove dip recess$4 space opening hole crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
-	0	(((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (gap groove dip recess$4 space opening hole crack)) and (wafer$4 layer$4 substrate$4 disk$4 film$4) same stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:31
-	1	(((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (gap groove dip recess$4 space opening hole crack)) and stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:31
-	0	(((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (gap groove dip recess$4 space opening hole crack)) and (wafer$4 layer$4 substrate$4 disk$4 film$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:34
-	1964	(((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (gap groove dip recess$4 space opening hole crack)) and (wafer$4 layer$4 substrate$4 disk$4 film$4) (bond$4 adhere$4 stick$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
-	2823	((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (wafer$4 layer$4 substrate$4 disk$4 film$4) (bond$4 adhere$4 stick$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:35
-	0	((thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) near3 gas) and (wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:36
-	103	(wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:46
-	10	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction) and(thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:37
-	10	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction) and (thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:43
-	2	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction) and (thermal heat) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:42
-	36	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction) and (thermal heat$4) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:43

-	11	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 stiction) and (thermal heat$4) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:48
-	1708	(wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 (stiction friction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:48
-	15	((wafer$4 layer$4 substrate$4 disk$4 film$4) same (bond$4 adhere$4 stick$4) near3 (stiction friction)) and (thermal heat$4) near3 (sens$4 measur$4 test identif$4 detect$4 determin$4 monitor$4 comput$4 calculat$4 indicat$4 evaluat$4 estimat$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 11:57

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